

74LVT16245B; 74LVTH16245B

3.3 V 16-bit transceiver; 3-state

Rev. 10 — 1 March 2012

Product data sheet

1. General description

The 74LVT16245B; 74LVTH16245B is a high-performance BiCMOS product designed for V_{CC} operation at 3.3 V.

This device is a 16-bit transceiver featuring non-inverting 3-state bus compatible outputs in both send and receive directions. The control function implementation minimizes external timing requirements. The device features an output enable input ($\overline{nOE}$) for easy cascading and a direction input ($nDIR$) for direction control.

2. Features and benefits

- 16-bit bidirectional bus interface
- 3-state buffers
- Output capability: +64 mA and –32 mA
- TTL input and output switching levels
- Input and output interface capability to systems at 5 V supply
- Bus hold data inputs eliminate need for external pull-up resistors to hold unused inputs
- Live insertion and extraction permitted
- Power-up 3-state
- No bus current loading when output is tied to 5 V bus
- Latch-up protection:
 - ◆ JESD78B Class II exceeds 500 mA
- ESD protection:
 - ◆ HBM JESD22-A114F exceeds 2000 V
 - ◆ MM JESD22-A115-A exceeds 200 V

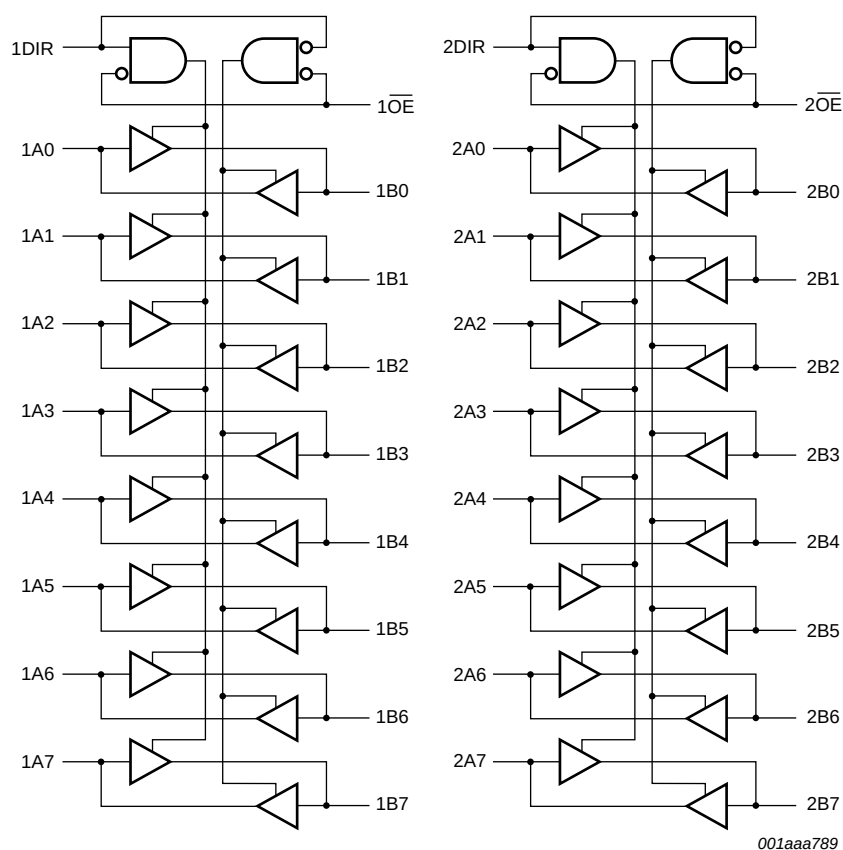


3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74LVT16245BDL 74LVTH16245BDL	–40 °C to +85 °C	SSOP48	plastic shrink small outline package; 48 leads; body width 7.5 mm	SOT370-1
74LVT16245BDGG 74LVTH16245BDGG	–40 °C to +85 °C	TSSOP48	plastic thin shrink small outline package; 48 leads; body width 6.1 mm	SOT362-1
74LVT16245BEV	–40 °C to +85 °C	VFBGA56	plastic very thin fine-pitch ball grid array package; 56 balls; body 4.5 × 7 × 0.65 mm	SOT702-1
74LVT16245BBX 74LVTH16245BBX	–40 °C to +125 °C	HXQFN60	plastic compatible thermal enhanced extremely thin quad flat package; no leads; 60 terminals; body 4 × 6 × 0.5 mm	SOT1134-2

4. Functional diagram



Pin numbers are shown for SSOP48 and TSSOP48 packages only.

Fig 1. Logic symbol

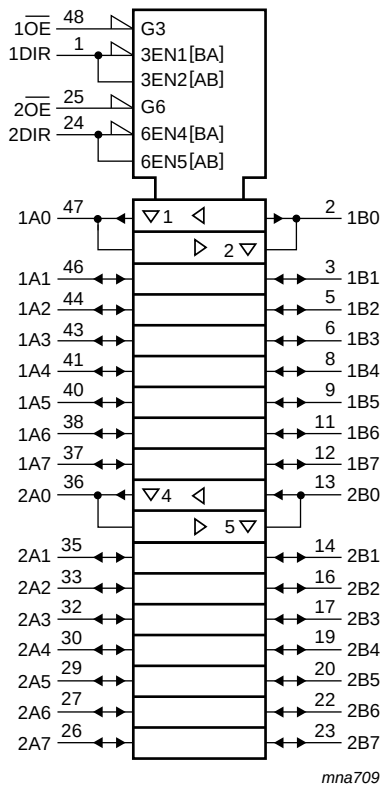
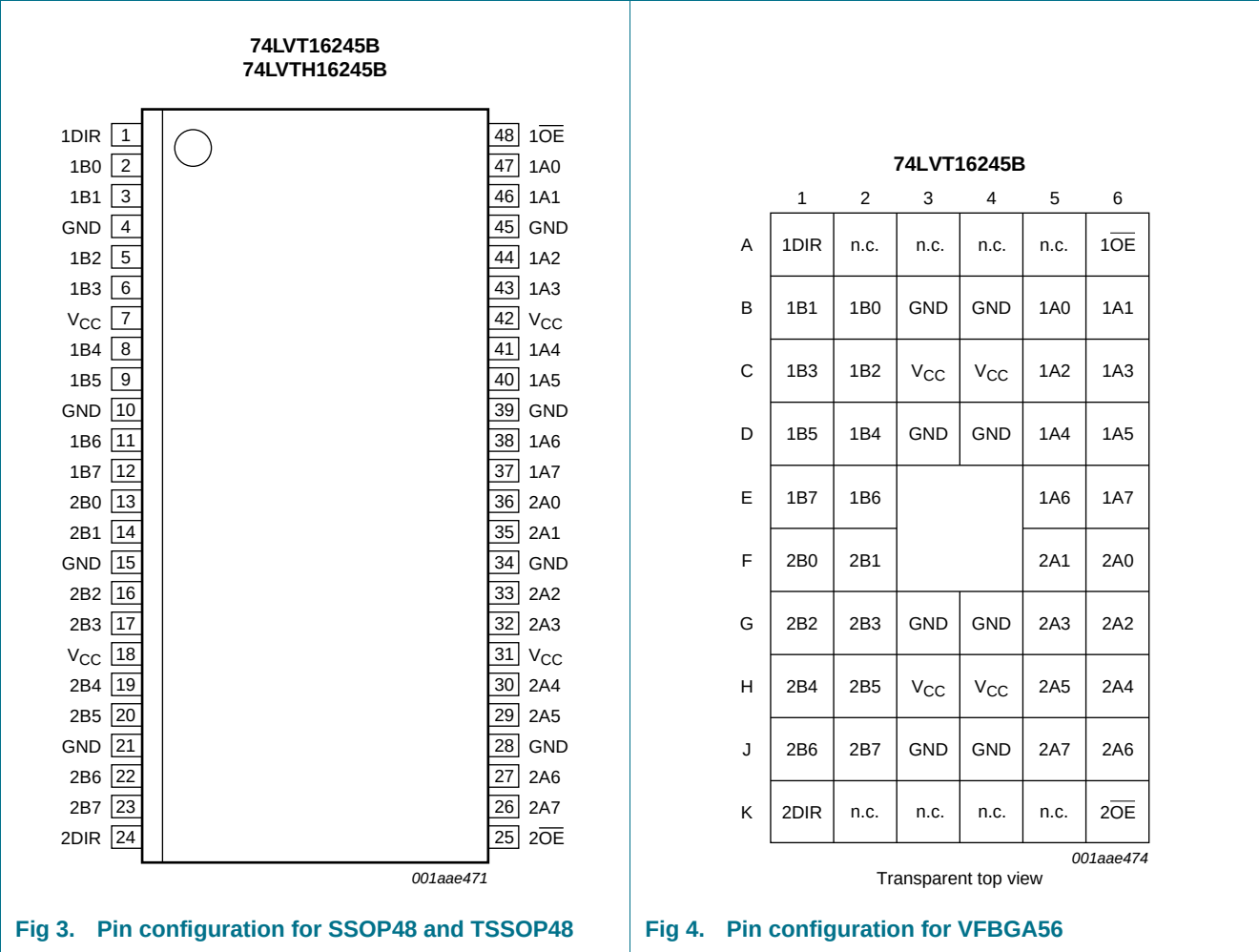
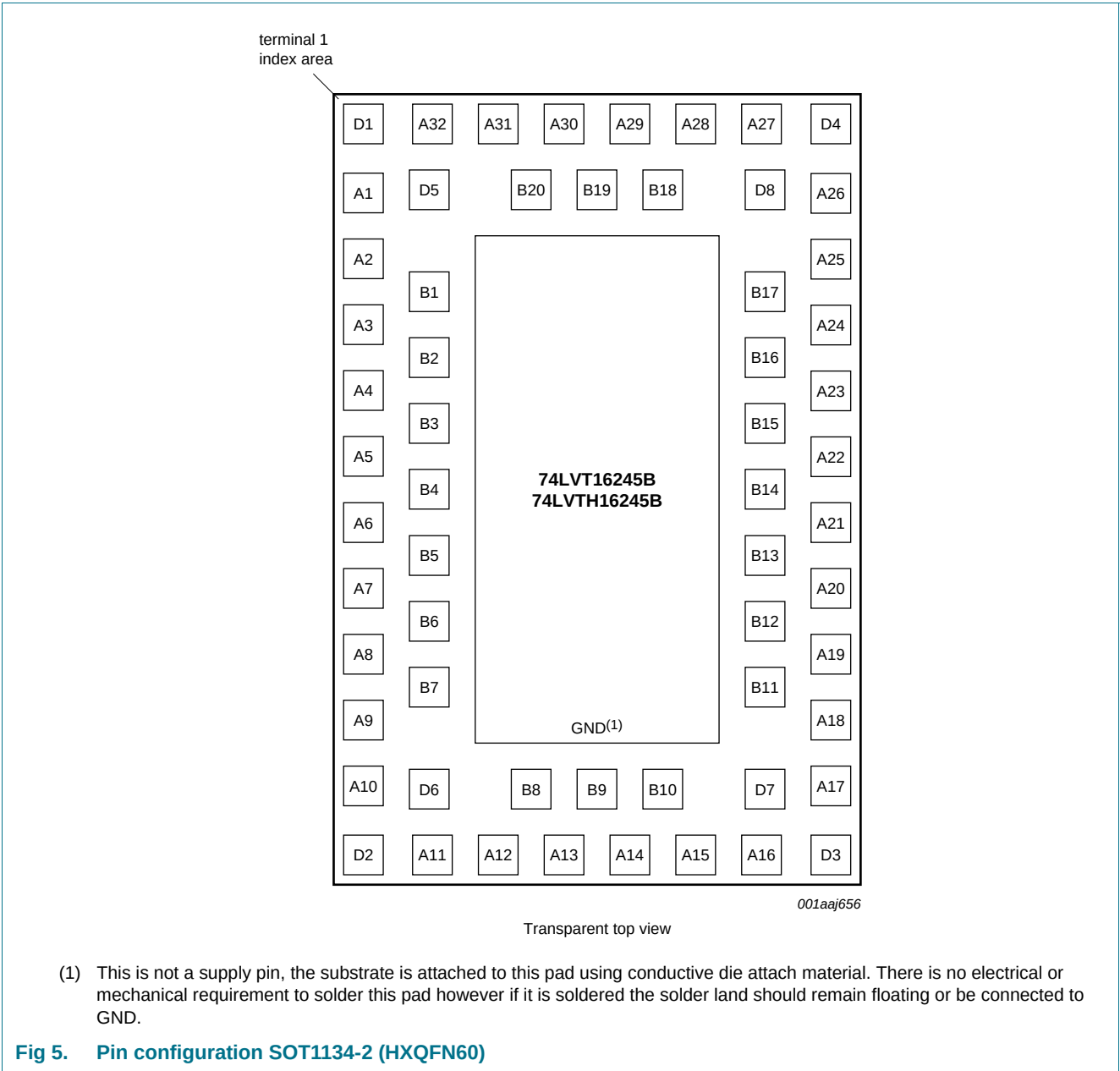


Fig 2. IEC logic symbol

5. Pinning information

5.1 Pinning





5.2 Pin description

Table 2. Pin description

Symbol	Pin			Description
	SOT370-1 and SOT362-1	SOT702-1	SOT1134-2	
1DIR, 2DIR	1, 24	A1, K1	A30, A13	direction control input
1B0 to 1B7	2, 3, 5, 6, 8, 9, 11, 12	B2, B1, C2, C1, D2, D1, E2, E1	B20, A31, D5, D1, A2, B2, B3, A5	data input/output
2B0 to 2B7	13, 14, 16, 17, 19, 20, 22, 23	F1, F2, G1, G2, H1, H2, J1, J2	A6, B5, B6, A9, D2, D6, A12, B8	data input/output
GND	4, 10, 15, 21, 28, 34, 39, 45	B3, D3, G3, J3, J4, G4, D4, B4	A32, A3, A8, A11, A16, A19, A24, A27	ground (0 V)
V _{CC}	7, 18, 31, 42	C3, H3, H4, C4	A1, A10, A17, A26	supply voltage
1OE, 2OE	48, 25	A6, K6	A29, A14	output enable input (active LOW)
2A0 to 2A7	36, 35, 33, 32, 30, 29, 27, 26	F6, F5, G6, G5, H6, H5, J6, J5	A21, B13, B12, A18, D3, D7, A15, B10	data input/output
1A0 to 1A7	47, 46, 44, 43, 41, 40, 38, 37	B5, B6, C5, C6, D5, D6, E5, E6	B18, A28, D8, D4, A25, B16, B15, A22	data input/output
n.c.	-	A2, A3, A4, A5, K2, K3, K4, K5	A4, A7, A20, A23, B1, B4, B7, B9, B11, B14, B17, B19	not connected

6. Functional description

6.1 Function table

Table 3. Function table [\[1\]](#)

Control		Input/output	
nOE	nDIR	nAn	nBn
L	L	output nAn = nBn	input
L	H	input	output nBn = nAn
H	X	Z	Z

- [1] H = HIGH voltage level;
 L = LOW voltage level;
 X = don't care;
 Z = high-impedance OFF-state.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		-0.5	+4.6	V
V_I	input voltage		[1] -0.5	+7.0	V
V_O	output voltage	output in OFF-state or HIGH-state	[1] -0.5	+7.0	V
I_{IK}	input clamping current	$V_I < 0$ V	-50	-	mA
I_{OK}	output clamping current	$V_O < 0$ V	-50	-	mA
I_O	output current	output in LOW-state	-	128	mA
		output in HIGH-state	-64	-	mA
T_{stg}	storage temperature		-65	+150	°C
T_j	junction temperature		[2] -	150	°C
P_{tot}	total power dissipation	$T_{amb} = -40$ °C to +85 °C;			
		(T)SSOP48 package	[3] -	500	mW
		VFBGA56 package	[4] -	1000	mW
		HXQFN60 package	[4] -	1000	mW

[1] The input and output negative voltage ratings may be exceeded if the input and output clamp current ratings are observed.

[2] The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability.

[3] Above 60 °C the value of P_{tot} derates linearly with 5.5 mW/K.

[4] Above 70 °C the value of P_{tot} derates linearly with 1.8 mW/K.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CC}	supply voltage		2.7	-	3.6	V
V_I	input voltage		0	-	5.5	V
V_{IH}	HIGH-level input voltage		2.0	-	-	V
V_{IL}	LOW-level input voltage		-	-	0.8	V
I_{OH}	HIGH-level output current		-32	-	-	mA
I_{OL}	LOW-level output current	none	-	-	32	mA
		current duty cycle ≤ 50 %; $f_i \geq 1$ kHz	-	-	64	mA
T_{amb}	ambient temperature	in free-air	-40	-	+85	°C
$\Delta t/\Delta V$	input transition rise and fall rate	outputs enabled	-	-	10	ns/V

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
T_{amb} = –40 °C to +85 °C ^[1]						
V _{IK}	input clamping voltage	V _{CC} = 2.7 V; I _{IK} = –18 mA	–1.2	–0.85	–	V
V _{OH}	HIGH-level output voltage	I _{OH} = –100 µA; V _{CC} = 2.7 V to 3.6 V	V _{CC} – 0.2	V _{CC}	–	V
		I _{OH} = –8 mA; V _{CC} = 2.7 V	2.4	2.5	–	V
		I _{OH} = –32 mA; V _{CC} = 3.0 V	2.0	2.3	–	V
V _{OL}	LOW-level output voltage	V _{CC} = 2.7 V				
		I _{OL} = 100 µA	–	0.07	0.2	V
		I _{OL} = 24 mA	–	0.3	0.5	V
		V _{CC} = 3.0 V				
		I _{OL} = 16 mA	–	0.25	0.4	V
		I _{OL} = 32 mA	–	0.3	0.5	V
I _I	input leakage current	control pins				
		V _{CC} = 3.6 V; V _I = V _{CC} or GND	–	0.1	±1	µA
		V _{CC} = 0 V or 3.6 V; V _I = 5.5 V	–	0.1	10	µA
		input/output data pins; V _{CC} = 3.6 V				
		V _I = 5.5 V	–	0.1	20	µA
		V _I = V _{CC}	–	0.5	10	µA
I _{OFF}	power-off leakage current	V _{CC} = 0 V; V _I or V _O = 0 V to 4.5 V	–	0.1	±100	µA
		V _{CC} = 3 V; V _I = 0.8 V				
		V _{CC} = 3 V; V _I = 2.0 V	–	–135	–75	µA
		nAn input; V _I = 0 V to 3.6 V; V _{CC} = 3.6 V	500	–	–	µA
		nAn input; V _I = 0 V to 3.6 V; V _{CC} = 3.6 V	–	–	–500	µA
		V _{CC} = 3.6 V; V _I = GND or V _{CC} ; I _O = 0 A				
I _{LO}	output leakage current	output in HIGH-state when V _O > V _{CC} ; V _O = 5.5 V; V _{CC} = 3.0 V	–	75	125	µA
I _{O(pu/pd)}	power-up/power-down output current	V _{CC} ≤ 1.2 V; V _O = 0.5 V to V _{CC} ; V _I = GND or V _{CC} ; nOE = don't care	–	40	±100	µA
I _{CC}	supply current	V _{CC} = 3.6 V; V _I = GND or V _{CC} ; I _O = 0 A				
		outputs HIGH	–	0.07	0.12	mA
		outputs LOW	–	4.7	6.0	mA
		outputs disabled	–	0.07	0.12	mA
ΔI _{CC}	additional supply current	per input pin; V _{CC} = 3.0 V to 3.6 V; one input at V _{CC} – 0.6 V, other inputs at V _{CC} or GND	–	0.1	0.2	mA
C _I	input capacitance	pins nDIR and nOE, V _O = 0 V or 3.0 V	–	3	–	pF

Table 6. Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$C_{io(off)}$	off-state input/output capacitance	pins nAn and nBn, outputs disabled; $V_O = GND$ or V_{CC}	-	9	-	pF

- [1] Typical values are measured at $V_{CC} = 3.3$ V and at $T_{amb} = 25$ °C.
- [2] Unused pins at V_{CC} or GND.
- [3] This is the bus hold overdrive current required to force the input to the opposite logic state.
- [4] This parameter is valid for any V_{CC} between 0 V and 1.2 V with a transition time of up to 10 ms. From $V_{CC} = 1.2$ V to $V_{CC} = 3.3$ V ± 0.3 V a transition time of 100 μ s is permitted. This parameter is valid for $T_{amb} = 25$ °C only.
- [5] I_{CC} is measured with outputs pulled to V_{CC} or GND.
- [6] This is the increase in supply current for each input at the specified voltage level other than V_{CC} or GND.

10. Dynamic characteristics

Table 7. Dynamic characteristicsVoltages are referenced to GND (ground = 0 V); for test circuit see [Figure 8](#).

Symbol	Parameter	Conditions	Min	Typ ^[1]	Max	Unit
$T_{amb} = -40$ °C to $+85$ °C						
t_{PLH}	LOW to HIGH propagation delay	nAn to nBn or nBn to nAn; see Figure 6				
		$V_{CC} = 2.7$ V	-	-	3.5	ns
		$V_{CC} = 3.0$ V to 3.6 V	1.0	1.9	3.3	ns
t_{PHL}	HIGH to LOW propagation delay	nAn to nBn or nBn to nAn; see Figure 6				
		$V_{CC} = 2.7$ V	-	-	3.5	ns
		$V_{CC} = 3.0$ V to 3.6 V	1.0	1.7	3.3	ns
t_{PZH}	OFF-state to HIGH propagation delay	$\overline{nOE}$ to nAn or nBn; see Figure 7				
		$V_{CC} = 2.7$ V	-	-	5.3	ns
		$V_{CC} = 3.0$ V to 3.6 V	1.0	2.8	4.5	ns
t_{PZL}	OFF-state to LOW propagation delay	$\overline{nOE}$ to nAn or nBn; see Figure 7				
		$V_{CC} = 2.7$ V	-	-	5.1	ns
		$V_{CC} = 3.0$ V to 3.6 V	1.0	2.8	4.1	ns
t_{PHZ}	HIGH to OFF-state propagation delay	$\overline{nOE}$ to nAn or nBn; see Figure 7				
		$V_{CC} = 2.7$ V	-	-	5.7	ns
		$V_{CC} = 3.0$ V to 3.6 V	1.5	3.2	5.1	ns
t_{PLZ}	LOW to OFF-state propagation delay	$\overline{nOE}$ to nAn or nBn; see Figure 7				
		$V_{CC} = 2.7$ V	-	-	4.6	ns
		$V_{CC} = 3.0$ V to 3.6 V	1.5	3.0	4.6	ns

- [1] All typical values are at $V_{CC} = 3.3$ V and $T_{amb} = 25$ °C.

11. Waveforms

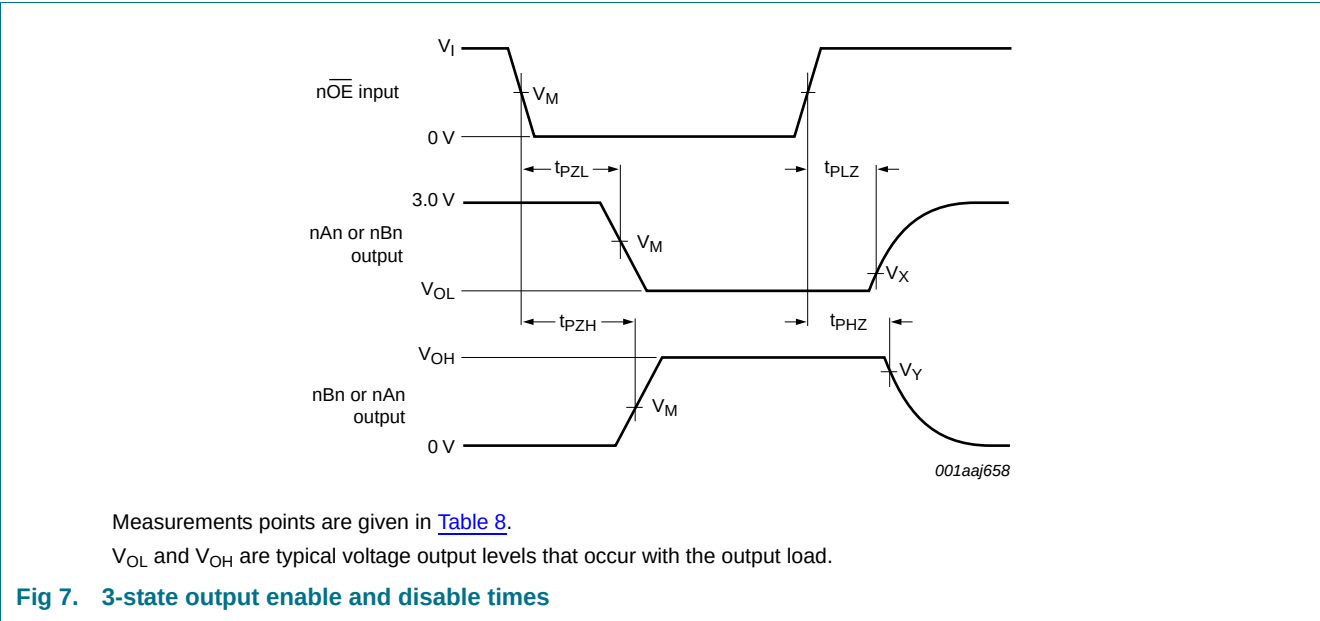
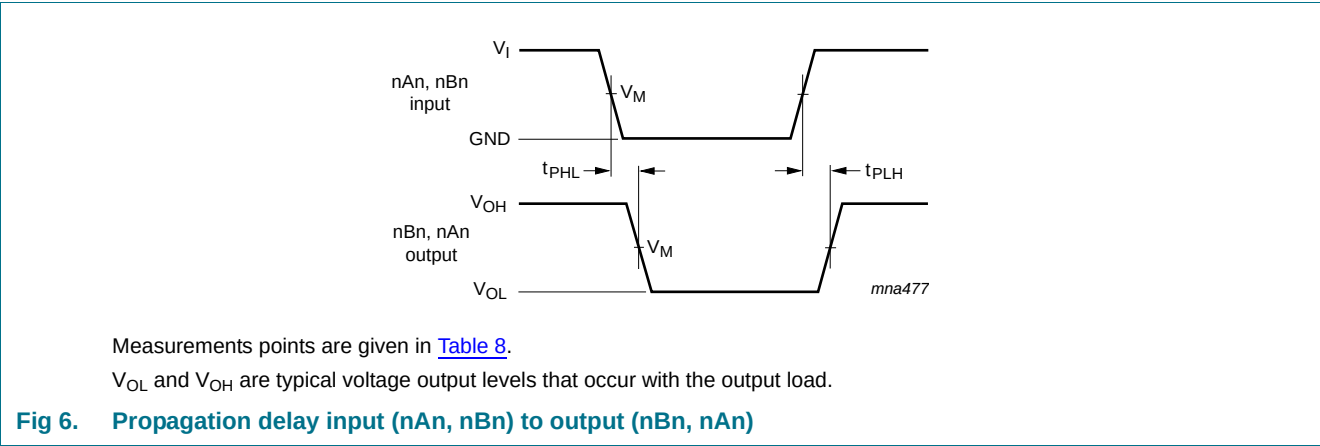


Table 8. Measurement points

Input	Output		
V_M	V_M	V_X	V_Y
1.5 V	1.5 V	$V_{OL} + 0.3\text{ V}$	$V_{OH} - 0.3\text{ V}$

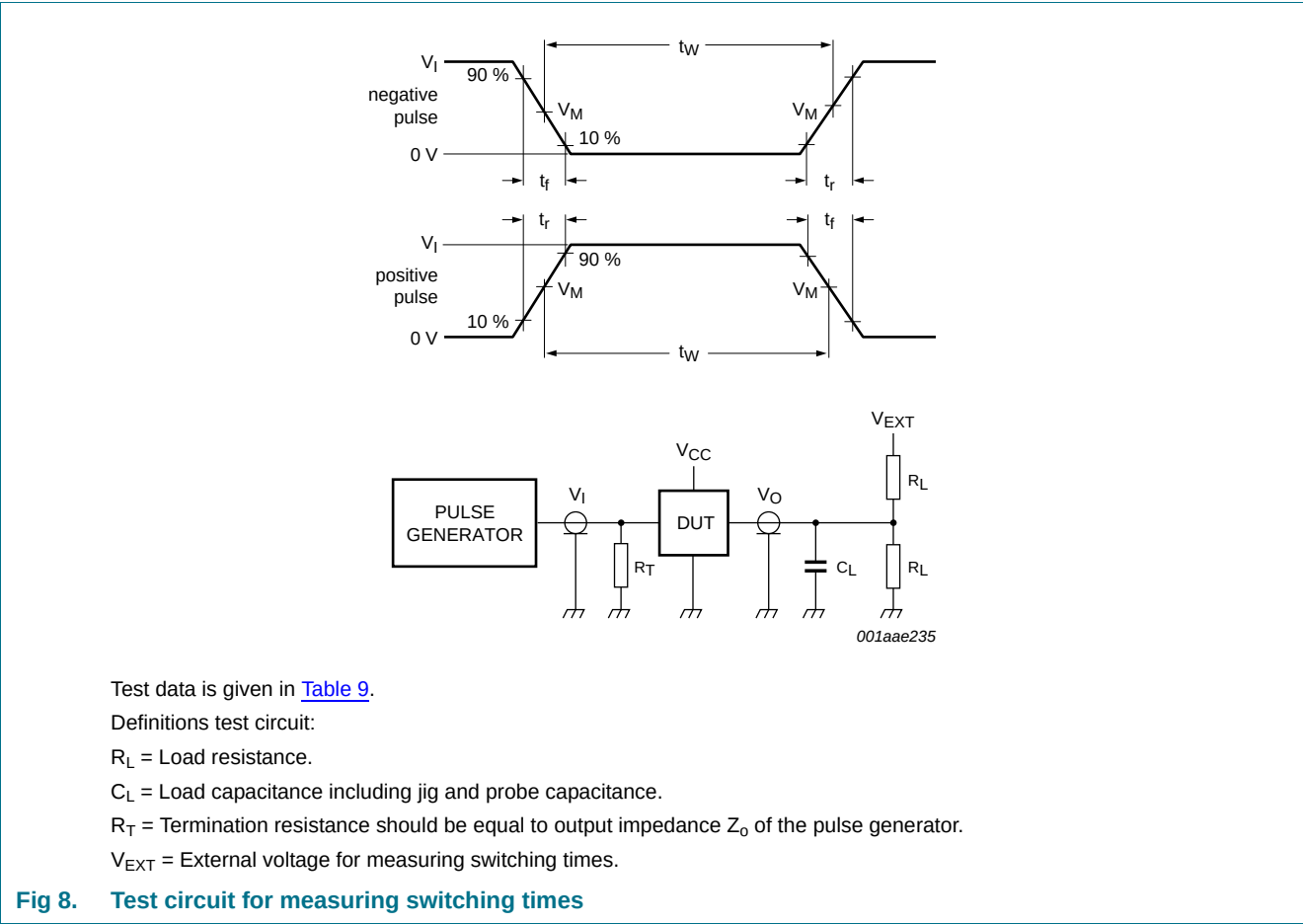


Table 9. Test data

Input				Load		V_{EXT}		
V_I	f_i	t_W	t_r, t_f	C_L	R_L	t_{PHZ}, t_{PZH}	t_{PLZ}, t_{PZL}	t_{PLH}, t_{PHL}
2.7 V	≤ 10 MHz	500 ns	≤ 2.5 ns	50 pF	500 Ω	GND	6 V	open

12. Package outline

SSOP48: plastic shrink small outline package; 48 leads; body width 7.5 mm SOT370-1

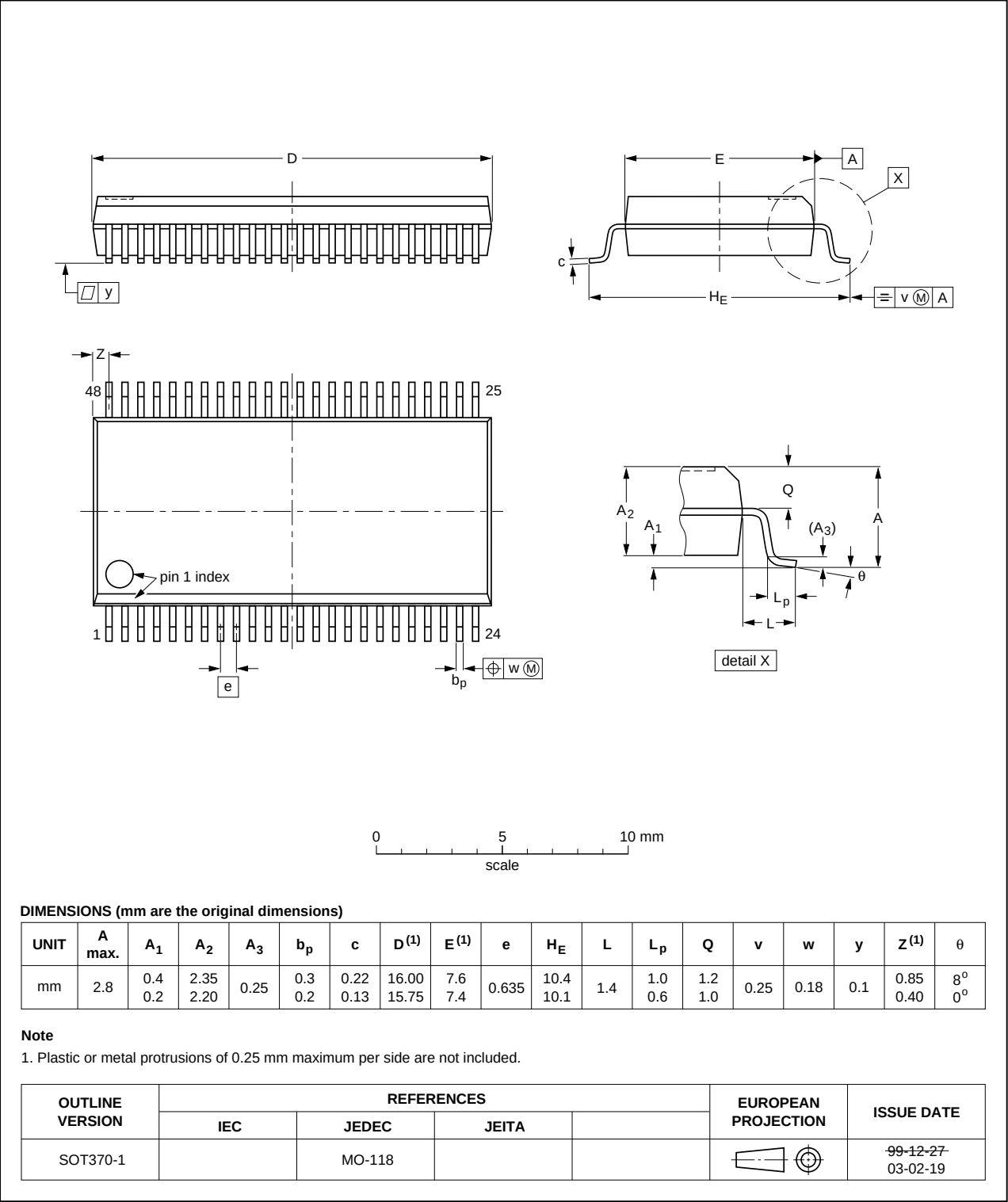


Fig 9. Package outline SOT370-1 (SSOP48)

TSSOP48: plastic thin shrink small outline package; 48 leads; body width 6.1 mm

SOT362-1

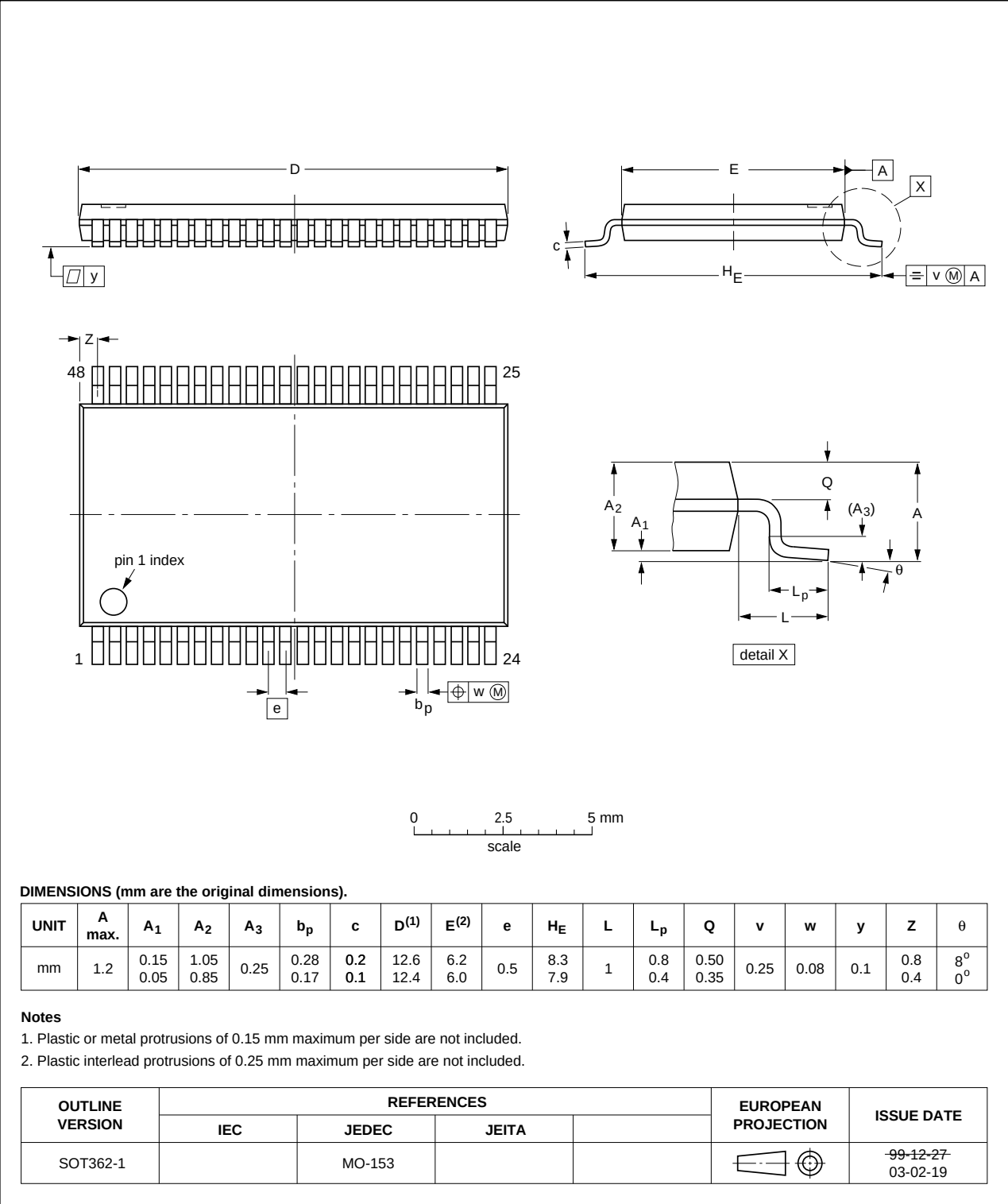


Fig 10. Package outline SOT362-1 (TSSOP48)

VFBGA56: plastic very thin fine-pitch ball grid array package; 56 balls; body 4.5 x 7 x 0.65 mm

SOT702-1

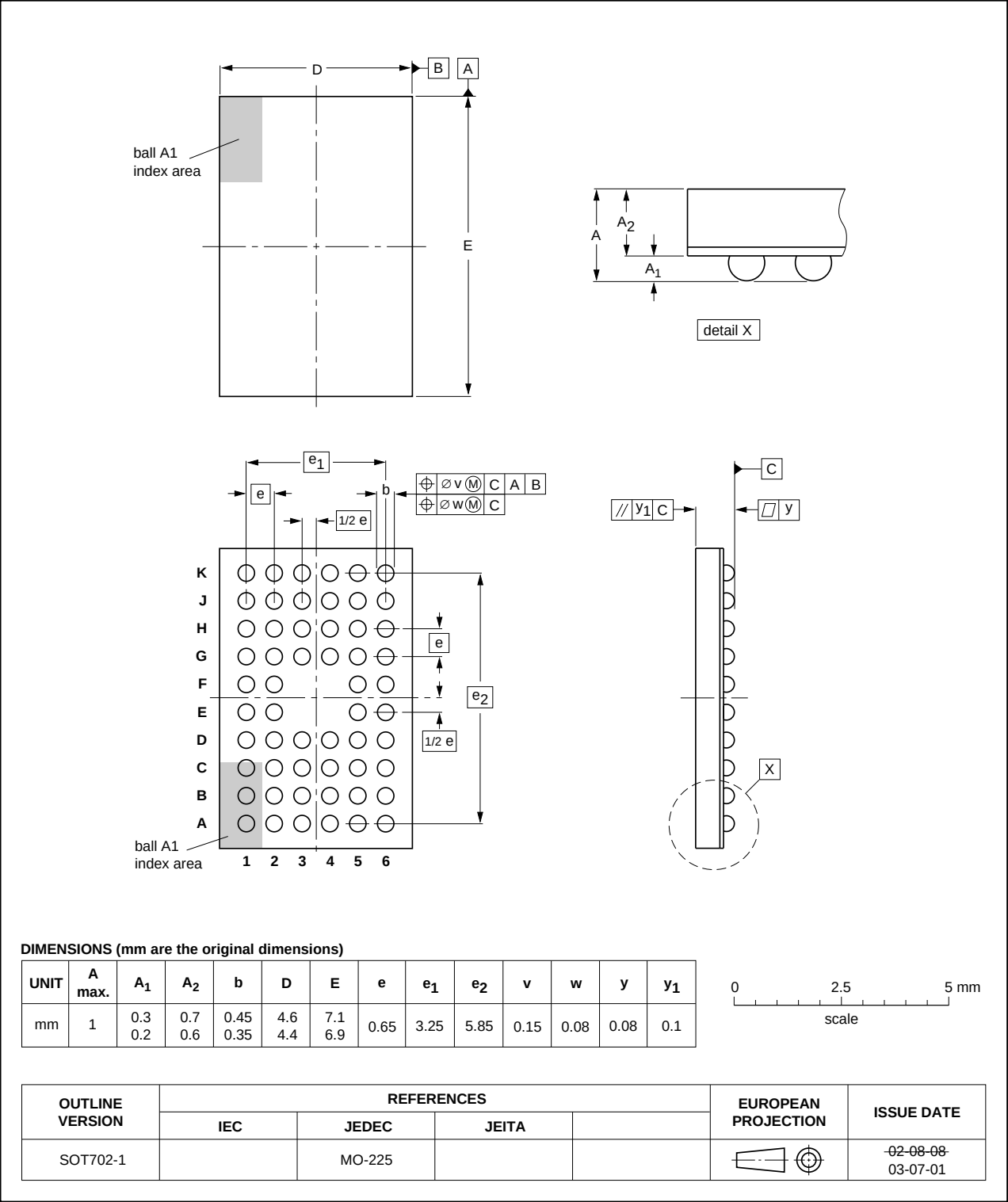


Fig 11. Package outline SOT702-1 (VFBGA56)

HXQFN60: plastic compatible thermal enhanced extremely thin quad flat package; no leads;
60 terminals; body 4 x 6 x 0.5 mm

SOT1134-2

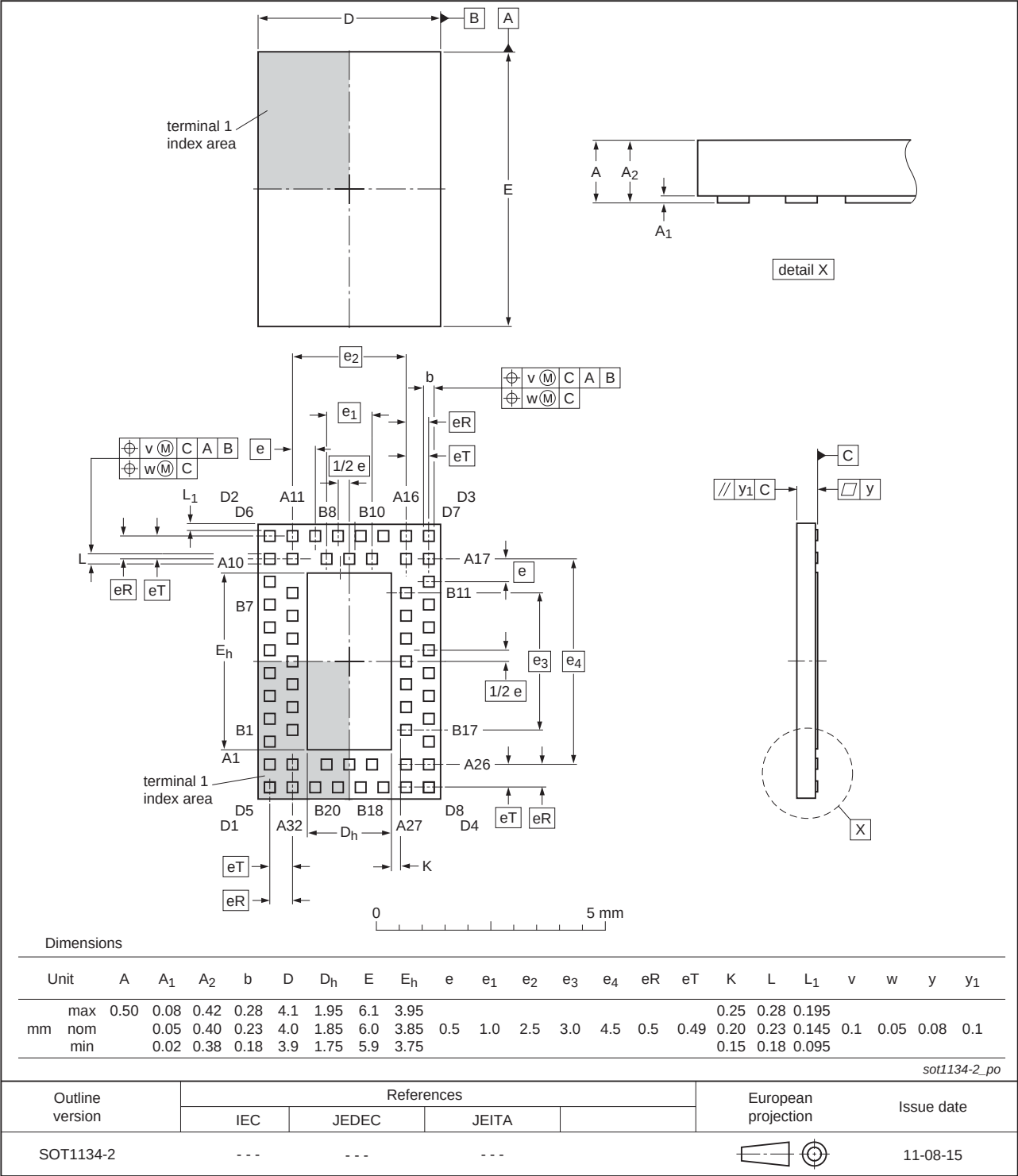


Fig 12. Package outline SOT1134-2 (HXQFN60)

13. Abbreviations

Table 10. Abbreviations

Acronym	Description
BICMOS	Bipolar Complementary Metal Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74LVT_LVTH16245B v.10	20120301	Product data sheet	-	74LVT_LVTH16245B v.9
Modifications:	For type number 74LVT16245BBX and 74LVTH16245BBX the sot code has changed to SOT1134-2.			
74LVT_LVTH16245B v.9	20111122	Product data sheet	-	74LVT_LVTH16245B v.8
Modifications:	Legal pages updated.			
74LVT_LVTH16245B v.8	20110617	Product data sheet	-	74LVT_LVTH16245B v.7
74LVT_LVTH16245B v.7	20100329	Product data sheet	-	74LVT_LVTH16245B v.6
74LVT_LVTH16245B v.6	20090409	Product data sheet	-	74LVT_LVTH16245B v.5
74LVT_LVTH16245B v.5	20090312	Product data sheet	-	74LVT_LVTH16245B v.4
74LVT_LVTH16245B v.4	20060323	Product data sheet	-	74LVT16245B v.3
74LVT16245B v.3	20021031	Product data sheet	-	74LVT16245B v.2
74LVT16245B v.2	19980219	Product specification	-	74LVT16245B v.1
74LVT16245B v.1	19940523	Product specification	-	-

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15.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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